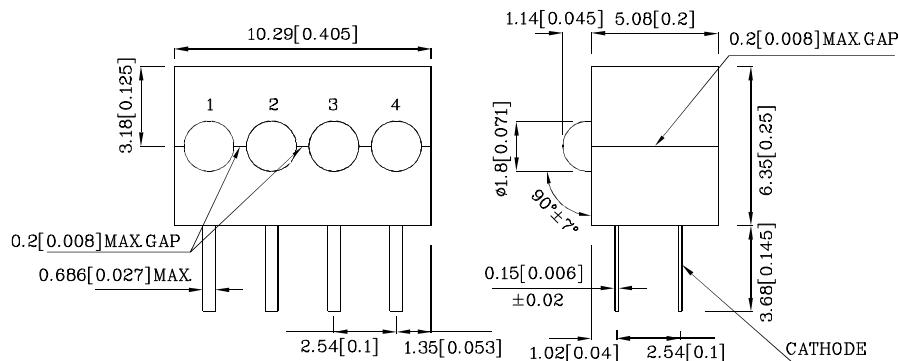


Features

- Housing material: Type 66 Nylon
- Black casing provides superior contrast
- Housing UL rating: 94V-0
- Reliable & robust
- Custom color combinations available
- RoHS Compliant


Package Schematics

Notes:

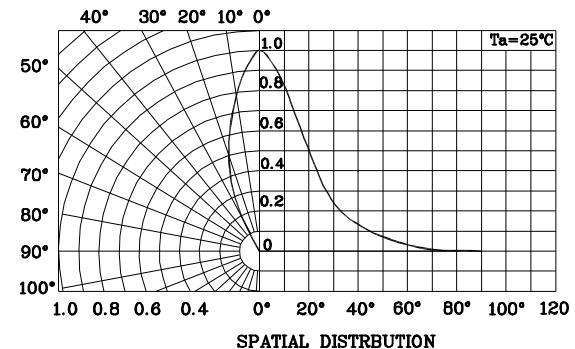
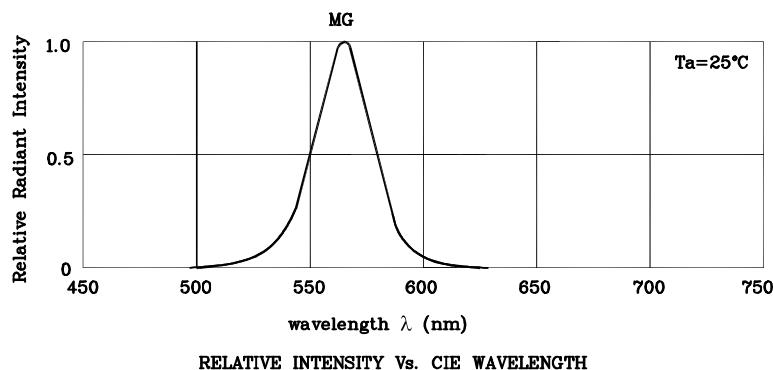
1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
3. Specifications are subject to change without notice.

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$)		MG (GaP)	Unit	
Reverse Voltage	V_R	5	V	
Forward Current	I_F	25	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{fs}	140	mA	
Power Dissipation	P_D	62.5	mW	
Operating Temperature	T_A	-40 ~ +85	$^\circ\text{C}$	
Storage Temperature	T_{stg}	-40 ~ +85		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds			
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds			

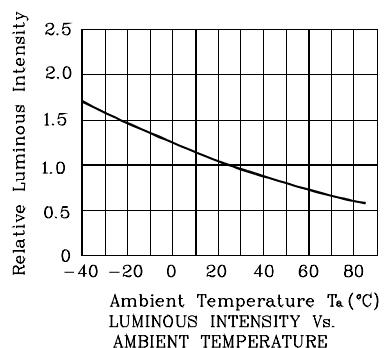
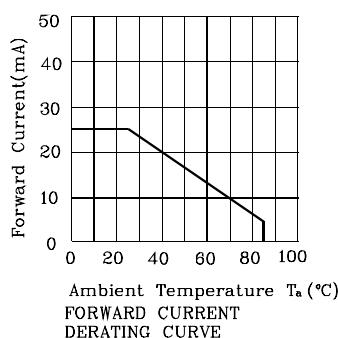
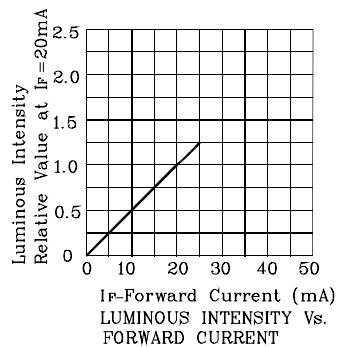
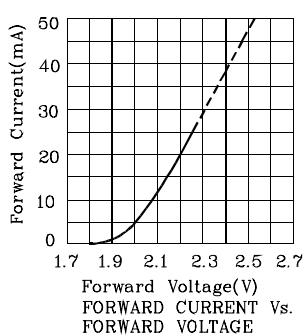
Operating Characteristics ($T_A=25^\circ\text{C}$)		MG (GaP)	Unit
Forward Voltage (Typ.) ($I_F=20\text{mA}$)	V_F	2.2	V
Forward Voltage (Max.) ($I_F=20\text{mA}$)	V_F	2.5	V
Reverse Current (Max.) ($V_R=5\text{V}$)	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) ($I_F=20\text{mA}$)	λP	565*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) ($I_F=20\text{mA}$)	λD	568*	nm
Spectral Line Full Width At Half-Maximum (Typ.) ($I_F=20\text{mA}$)	$\Delta\lambda$	30	nm
Capacitance (Typ.) ($V_F=0\text{V}$, $f=1\text{MHz}$)	C	15	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* ($I_F=20\text{mA}$) mcd	Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
XNF4ZMG46D	Green	GaP	Green Diffused	5*	11*	565*

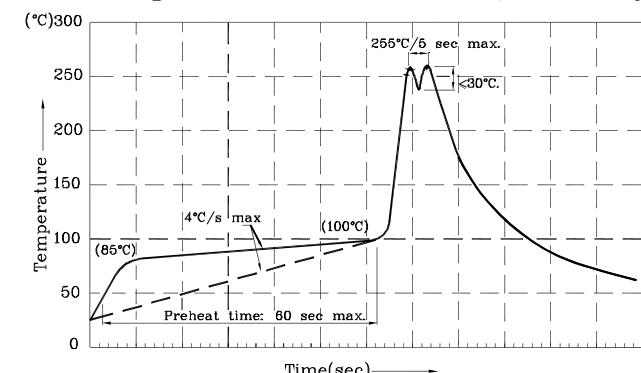
*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



❖ MG



Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes:

1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C.
2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

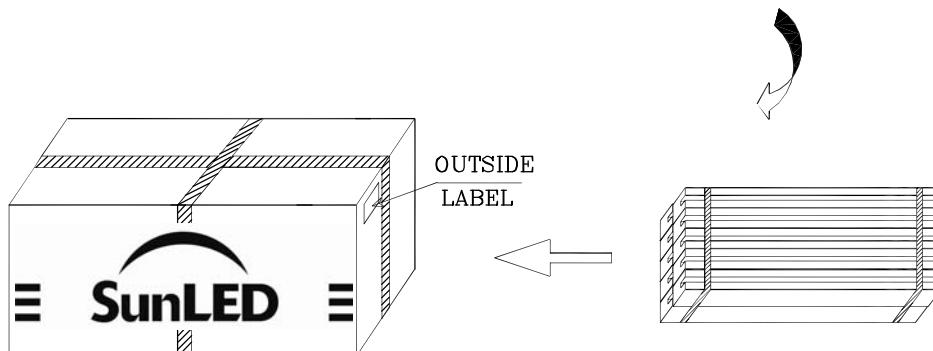
1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

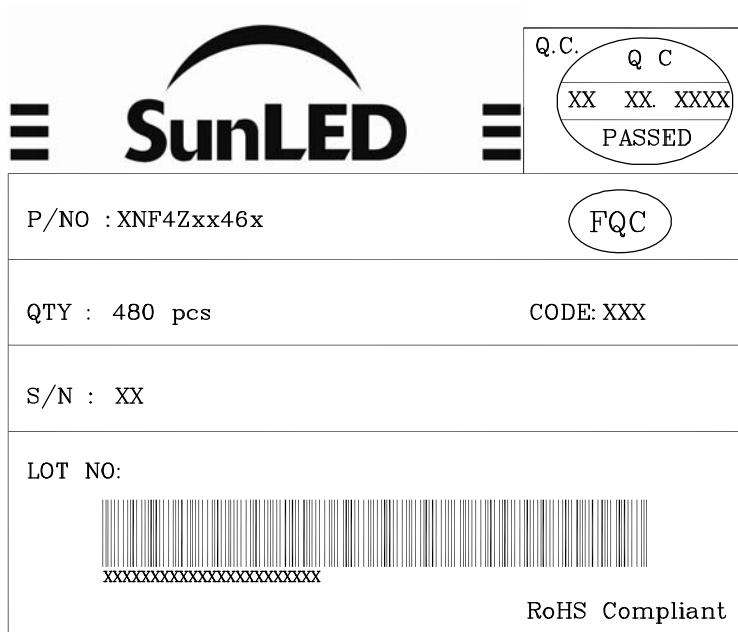


48PCS /IC TUBE



10.56K/BOX

480pcs/10pcs IC TUBE



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